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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/965,221	09/28/2001	Masakatsu Gotou	501.40695X00	3864

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EXAMINER

LATTIN, CHRISTOPHER W

ART UNIT PAPER NUMBER

2812

DATE MAILED: 03/03/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary

Application No.

09/965,221

Applicant(s)

GOTOU ET AL.

Examiner

Christopher W Lattin

Art Unit

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-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 09 December 2003.
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 29 and 31-60 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 29 and 31-60 is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on _____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some * c) ☐ None of:
- ☐ Certified copies of the priority documents have been received.
 - ☐ Certified copies of the priority documents have been received in Application No. _____.
 - ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- ☒ Notice of References Cited (PTO-892)
- ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- ☐ Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
Paper No(s)/Mail Date _____.
- ☐ Interview Summary (PTO-413)
Paper No(s)/Mail Date _____.
- ☐ Notice of Informal Patent Application (PTO-152)
- ☐ Other: _____.

DETAILED ACTION

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Claims 29, 31-33, 37-42, and 46-60 are rejected under 35 U.S.C. 103(a) as being unpatentable over Tsuruta (U.S. Patent 6,200,121) in view of Hashimoto (U.S. Patent 5,729,437) and Miyajima (U.S. Patent 6,344,162).

Tsuruta teach all of the limitations of the presently claimed manufacturing method including forming a resin enclosure for block-molding a plurality of semiconductor chips by placing a plurality of semiconductor chips inside a cavity of a molding die along and then injecting a resin inside said cavity from a first side to a second side of a main surface of the substrate, the plurality of semiconductor chips being mounted on the main surface of the substrate from the first side to the second side of the surface with a predetermined space, but fail to teach cleaning the surface of the substrate prior to placing it in the enclosure and the use of air vents. Hashimoto teach that "[I]f the surfaces of the substrate 6 and the semiconductor device 1 are activated with oxygen or argon plasma immediately before the process for applying the molding resin 5 is performed, further excellent contact of the molding resin 5 can be established. As a result the reliability of the electronic part can be improved more satisfactorily." See

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Hashimoto column 15 lines 14-20. It would have been obvious to one skilled in the art at the time of the invention to clean the substrate taught by Tsuruta prior to encapsulation to improve the contact of the molding resin and thus reliability of the electronic part as taught by Hashimoto.

Tsuruta also fails to specify how or if the chips are connected to substrates. Hashimoto teaches wire bonding to electrically connect the chips to the substrate. It would have been obvious to one skilled in the art at the time of the invention to utilize wire bonds to provide electrical connection the chips to the substrate. With reference to claims 31, 32, 40 and 41, roughening and impurity removal are inherent aspects of the plasma treatment process.

Tsuruta also fails to teach the use of air vents in the molding method. Miyajima teach the use of air vents 108 with regions 102 (which are similar in nature to dummy gate regions 21g of Tsuruta). It would have been obvious to one skilled in the art at the time of the invention to form air vents according to Miyajima to allow airflow throughout the mold of Tsuruta.

With particular reference to claims 38 and 47, though Tsuruta fail to specify heating, bump attachment is discussed at the top of column 5. Hashimoto teaches in column 13 that heating during the mounting step allows conductive paste to flow, and, upon cooling to attach to surfaces. It would have been obvious to one skilled in the art at the time of the invention to use a heating step during mounting to allow conductive material to attach to surfaces, an inherent part of the bumping method taught by Tsuruta.

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Claims 34-36, and 43-45 are rejected under 35 U.S.C. 103(a) as being unpatentable over Tsuruta in view of Hashimoto and Miyajima as applied above, and further in view of Ishikawa (U.S. Patent 5,939,792).

Tsuruta is applied in view of Hashimoto and Miyajima above and teach all of the limitations of the invention, but fail to teach the use of high volume amounts silica fillers in the resin. Ishikawa teaches the inclusion of large amounts silica filler in encapsulating resin to enhance the properties, such as water repellency, of the device. It therefore would have been obvious to one skilled in the art at the time of the invention to include high volume amounts of silica as taught by Ishikawa in the resin obviated by Tsuruta in view of Hashimoto.

Response to Arguments

Applicant argues that Hashimoto and Tsuruta are non-combinable because the deal with different types of molding. The references are combined for the teaching that it is well known to clean devices of debris prior to molding, whether the molding technique is ultimately the potting or block method. Further arguments regarded the flow characteristics desired using the claimed method. One skilled in the art at the time of the invention armed with the prior art cited above would have achieved the claimed method. The use of dummy gates, air vents and the claimed techniques are all well known in the art for forming superior molded devices.

With reference to the newly added claims, the use of air vents to ensure laminar flow on all sides of a mold are well known as addressed in the rejection above. The

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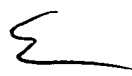
additional limitations of claims 57 and 58 would have been inherent as they describe the result of performing the obviated method.


Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Christopher Lattin whose telephone number is (571) 272-1673. The examiner can normally be reached Monday through Friday from 8:00 A.M. to 5:00 P.M.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, John Niebling, can be reached at (571) 272-1679. The fax number for this Group is (703) 872-9306.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the Group receptionist whose telephone number is (703) 308-0956.

CWL 
February 19, 2004


John F. Niebling
Supervisory Patent Examiner
Technology Center 2809